

Insulated Gate Bipolar Transistor (Ultrafast Speed IGBT), 100 A



PRIMARY CHARACTERISTICS					
V _{CES}	600 V				
V _{CE(on)} (typical)	1.92 V				
V_{GE}	15 V				
I _C	100 A				
Speed	8 kHz to 30 kHz				
Package	SOT-227				
Circuit configuration	Single switch no diode				

FEATURES

 Ultrafast: optimized for minimum saturation voltage and speed up to 30 kHz in hard switching, > 200 kHz in resonant mode



- Very low conduction and switching losses
- Fully isolate package (2500 V_{AC/RMS})
- Very low internal inductance (≤ 5 nH typical)
- Industry standard outline
- UL approved file E78996
- Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

BENEFITS

- Designed for increased operating efficiency in power conversion: UPS, SMPS, welding, induction heating
- Lower overall losses available at frequencies = 20 kHz
- Easy to assemble and parallel
- · Direct mounting to heatsink
- · Lower EMI, requires less snubbing
- Plug-in compatible with other SOT-227 packages

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Collector to emitter breakdown voltage	V_{CES}		600	V	
Continuous collector current	Ic	T _C = 25 °C	200		
		T _C = 100 °C	100		
Pulsed collector current	I _{CM}		400	Α	
Clamped inductive load current	I_{LM} $V_{CC} = 80 \% (V_{CES}), V_{GE} = 20 \text{ V}, L$ $R_g = 2.0 \Omega$, see fig. 13a		400		
Gate to emitter voltage	V_{GE}		± 20	V	
Reverse voltage avalanche energy	E _{ARV}	Repetitive rating; pulse width limited by maximum junction temperature	160	mJ	
RMS isolation voltage	V _{ISOL}	Any terminal to case, t = 1 min	2500	V	
Maximum power dissipation	P _D	T _C = 25 °C	500	W	
		T _C = 100 °C	200		
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C	
Mounting torque		6-32 or M3 screw	1.3 (12)	Nm (lbf.in)	

THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction and storage temperature range	T _J , T _{Stg}		-55	-	150	
Thermal resistance, junction to case	R _{thJC}		-	-	0.25	°C/W
Thermal resistance case to heatsink	R _{thCS}	Flat, greased, surface	-	0.05	-	
Weight			-	30	-	g
Mounting torque		Torque to terminal	-	-	1.1 (9.7)	Nm (lbf.in)
		Torque to heatsink	-	-	1.8 (15.9)	Nm (lbf.in)
Case style			SOT-227			



ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Collector to emitter breakdown voltage	V _{(BR)CES}	$V_{GE} = 0 \text{ V}, I_{C} = 250 \mu\text{A}$	600	-	-		
Emitter to collector breakdown voltage	V _{(BR)ECS}	$V_{GE} = 0 \text{ V}, I_{C} = 1.0 \text{ A}$ Pulse width $\leq 80 \mu\text{s}; \text{ duty}$	18	-	ı	V	
Temperature coefficient of breakdown voltage	$\Delta V_{(BR)CES}/\Delta T_{J}$	V _{GE} = 0 V, I _C = 10 mA		-	0.38	-	V/°C
Collector to emitter saturation voltage	V _{CE(on)}	I _C = 100 A	V _{GE} = 15 V See fig. 2, 5	ı	1.60	1.9	- V
		I _C = 200 A		ı	1.92	-	
		$I_C = 100 \text{ A}, T_J = 150 ^{\circ}\text{C}$		ı	1.54	-	
Gate threshold voltage	V _{GE(th)}	$V_{CE} = V_{GE}, I_{C} = 250 \mu A$		3.0	-	6.0	
Temperature coefficient of threshold voltage	$\Delta V_{GE(th)}/\Delta T_J$	$V_{CE} = V_{GE}$, $I_C = 2.0 \text{ mA}$		-	-11	-	mV/°C
Forward transconductance	g _{fe}	$V_{CE} = 100 \text{ V}, I_{C} = 100 \text{ A}$ Pulse width 5.0 µs, single shot		79	-	-	S
Zero gate voltage collector current	I _{CES}	V _{GE} = 0 V, V _{CE} = 600 V		-	-	1.0	mA
		$V_{GE} = 0 \text{ V}, V_{CE} = 600 \text{ V}, T_{J} = 150 ^{\circ}\text{C}$		-	-	10	IIIA
Gate to emitter leakage current	I _{GES}	$V_{GE} = \pm 20 \text{ V}$		-	-	± 250	nA

SWITCHING CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Total gate charge (turn-on)	Qg	I _C = 100 A	-	770	1200			
Gate-emitter charge (turn-on)	Q_ge	V _{CC} = 400 V	-	100	150	nC		
Gate-collector charge (turn-on)	Q_{gc}	V _{GE} = 15 V; See fig. 8	-	260	380			
Turn-on delay time	t _{d(on)}	T _{.1} = 25 °C	-	54	-			
Rise time	t _r	I _C = 100 A	-	79	-	ns		
Turn-off delay time	t _{d(off)}	V _{CC} = 480 V	-	130	200			
Fall time	t _f	V _{GE} = 15 V	-	300	450			
Turn-on switching loss	E _{on}	$R_g = 2.0 \Omega$	-	0.98	-			
Turn-off switching loss	E _{off}	Energy losses include "tail" See fig. 9, 10, 14	-	3.48	-	mJ		
Total switching loss	E _{ts}		-	4.46	7.6			
Turn-on delay time	t _{d(on)}	T _J = 150 °C	-	56	-			
Rise time	t _r	I_C = 100 A, V_{CC} = 480 V V_{GE} = 15 V, R_g = 2.0 Ω Energy losses include "tail"	-	75	-			
Turn-off delay time	t _{d(off)}		-	160	-	ns		
Fall time	t _f		-	460	-			
Total switching loss	E _{ts}	See fig. 10, 11, 14	-	7.24	-	mJ		
Internal emitter inductance	L _E	Measured 5 mm from package	-	5.0	_	nΗ		
Input capacitance	C _{ies}	V _{GE} = 0 V	-	16 500	-			
Output capacitance	C _{oes}	V _{CC} = 30 V	-	1000	_	рF		
Reverse transfer capacitance	C _{res}	f = 1.0 MHz; See fig. 7	-	200	-			



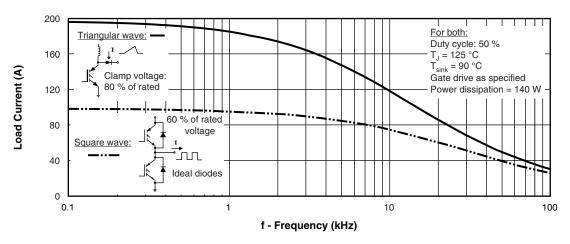


Fig. 1 - Typical Load Current vs. Frequency (Load Current = I_{RMS} of Fundamental)

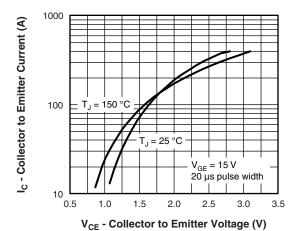


Fig. 2 - Typical Output Characteristics

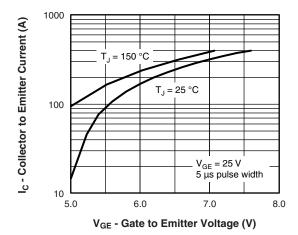


Fig. 3 - Typical Transfer Characteristics

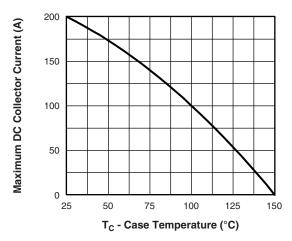


Fig. 4 - Maximum Collector Current vs. Case Temperature

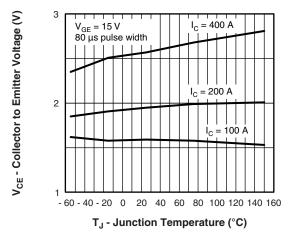


Fig. 5 - Typical Collector to Emitter Voltage vs. Junction Temperature



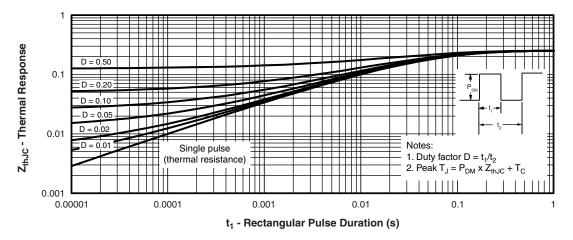


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction to Case

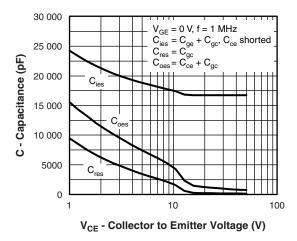


Fig. 7 - Typical Capacitance vs. Collector to Emitter Voltage

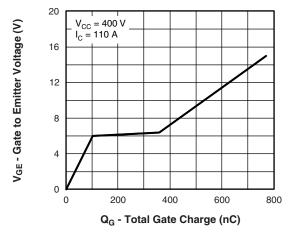


Fig. 8 - Typical Gate Charge vs. Gate to Emitter Voltage

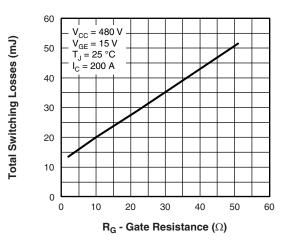


Fig. 9 - Typical Switching Losses vs. Gate Resistance

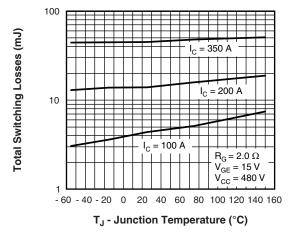


Fig. 10 - Typical Switching Losses vs. Junction Temperature

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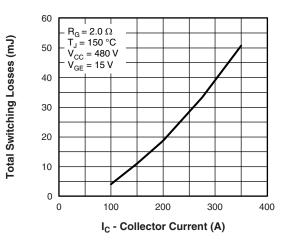


Fig. 11 - Typical Switching Losses vs. Collector Current

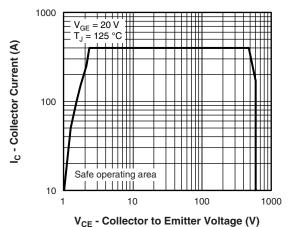
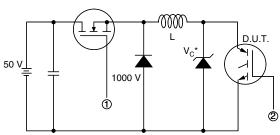


Fig. 12 - Turn-Off SOA



 * Driver same type as D.U.T.; $\rm V_{C}$ = 80 % of $\rm V_{CE}$ (max)

Note: Due to the 50 V power supply, pulse width and inductor will increase to obtain rated I_d

Fig. 13a - Clamped Inductive Load Test Circuit

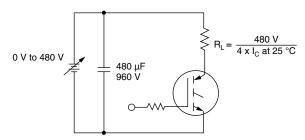


Fig. 13b - Pulsed Collector Current Test Circuit

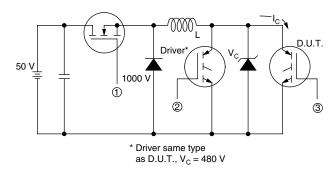


Fig. 14a - Switching Loss Test Circuit

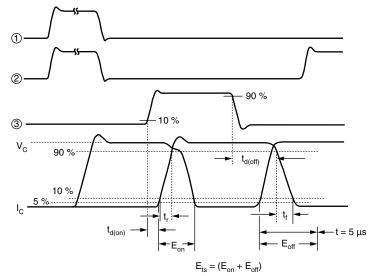
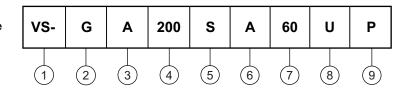


Fig. 14b - Switching Loss Waveforms



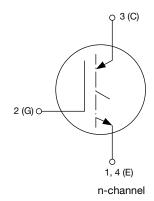
ORDERING INFORMATION TABLE

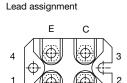
Device code



- 1 Vishay Semiconductors product
- Insulated gate bipolar transistor (IGBT)
- Generation 4, IGBT silicon, DBC construction
- 4 Current rating (200 = 200 A)
- 5 Single switch no diode
- 6 SOT-227
- 7 Voltage rating (60 = 600 V)
- Speed/type (U = ultrafast)
- 9 • None = standard production
 - P = lead (Pb)-free

CIRCUIT CONFIGURATION





 LINKS TO RELATED DOCUMENTS

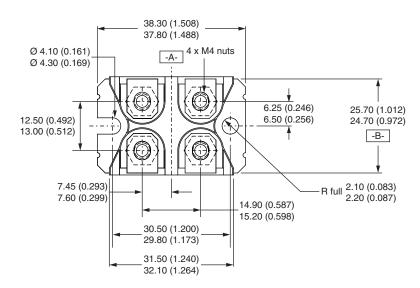
 Dimensions
 www.vishay.com/doc?95425

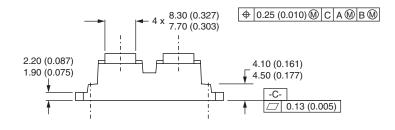
 Packaging information
 www.vishay.com/doc?95423

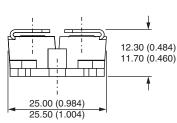


SOT-227 Generation II

DIMENSIONS in millimeters (inches)







Note

• Controlling dimension: millimeter



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